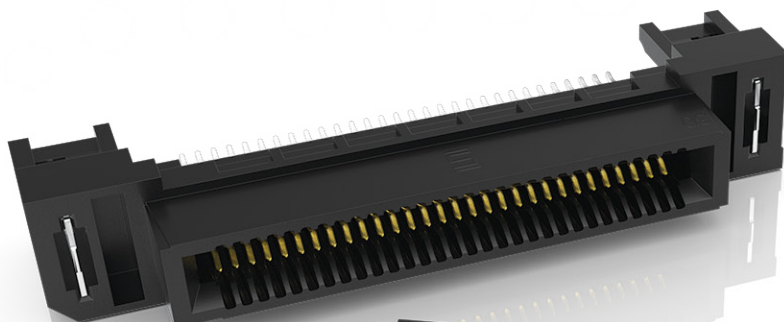


GENERATE[®]

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH

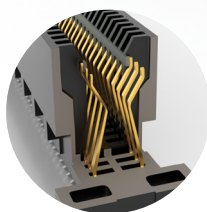
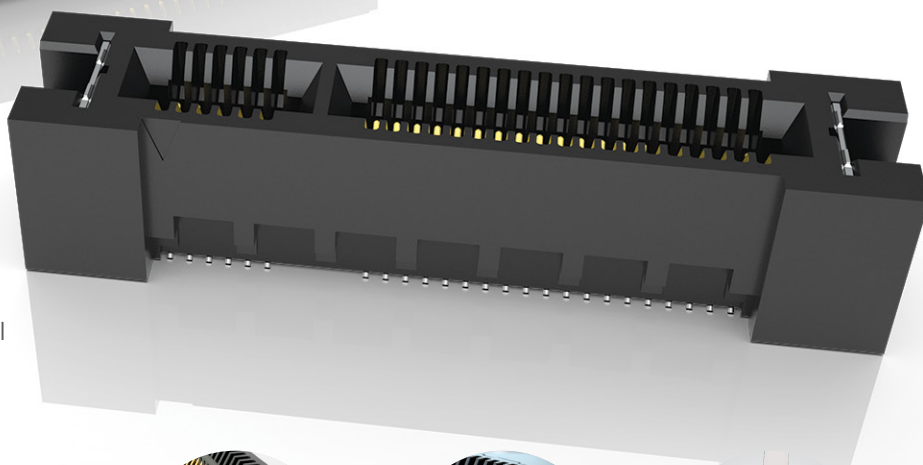


**EDGE
RATE[®]**
CONTACT

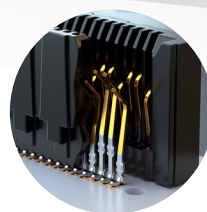
FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express[®] 3.0, 4.0, 5.0 and 6.0
- Edge Rate[®] contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

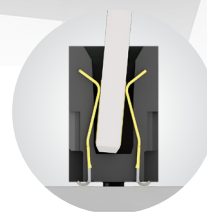
The PCI Express[®] design marks are registered trademarks and/or service marks of PCI-SIG.



Rugged tucked
beam technology
(HTEC8)



Differential pair for
increased speed
(HSEC8-DP)



Custom designs allow
for misalignment in
the X-Y axes (HSEC1)

KEY SPECIFICATIONS

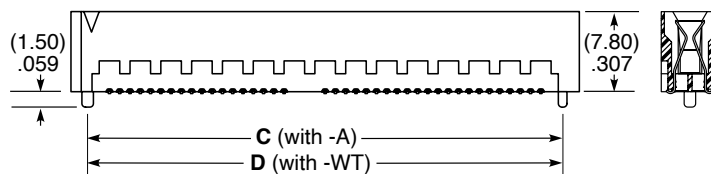
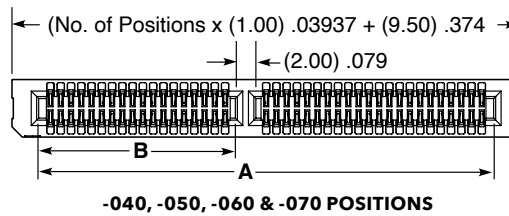
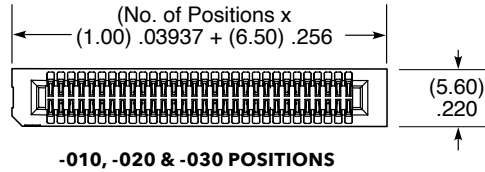
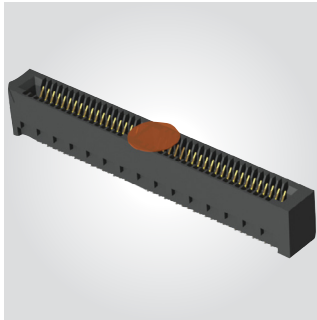
SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

1.00 mm (.0394") PITCH • VERTICAL HIGH-SPEED EDGE CARD

HSEC1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	OPTION	OTHER OPTION	"X"R
	-010, -020, -030, -040, -050, -060, -070	-01 =(1.60 mm) .062" thick card	-F = Gold flash on contact, Matte Tin on tail -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail		-A or -WT required in callout -A =Alignment Pin (Not available with -WT) -WT =Weld tab (Not available with -A)	-K =(7.01 mm) .276" DIA Polyimide Film Pick & Place Pad	-TR or -FR required for 10-60 positions. Leave blank for 70 positions. -TR =Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

HSEC1-DV

Card Mates:
(1.60 mm) .062"
thick card



POSITIONS PER ROW	A	B	C (with -A)	D (with -WT)
-010	(11.30) .445	N/A	(13.25) .522	(14.50) .571
-020	(21.30) .839	N/A	(23.25) .915	(24.50) .965
-030	(31.30) 1.232	N/A	(33.25) 1.309	(34.50) 1.358
-040	(44.30) 1.744	(19.15) .754	(46.25) 1.821	(47.50) 1.870
-050	(54.30) 2.138	(24.15) .951	(56.25) 2.215	(57.50) 2.264
-060	(64.30) 2.531	(29.15) 1.148	(66.25) 2.608	(67.50) 2.657
-070	(74.30) 2.925	(34.15) 1.344	(76.25) 3.002	(77.50) 3.051

Note:
Some sizes, styles and
options are non-standard,
non-returnable.

View complete specifications at: [samtec.com?HSEC1-DV](https://www.samtec.com?HSEC1-DV)